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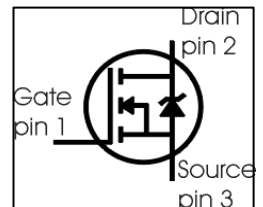
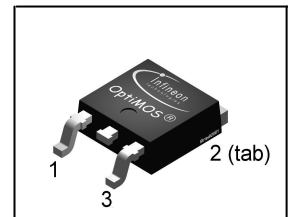
**OptiMOS® Power-Transistor**
**Feature**

- N-Channel
- Enhancement mode
- Logic Level
- Excellent Gate Charge x  $R_{DS(on)}$  product (FOM)
- Superior thermal resistance
- 175°C operating temperature
- Avalanche rated
- $dv/dt$  rated

**Product Summary**

$V_{DS}$	30	V
$R_{DS(on)}$	6.7	m $\Omega$
$I_D$	30	A

P- TO252 -3-11



Type	Package	Ordering Code	Marking
SPD30N03S2L-07	P- TO252 -3-11	Q67042-S4091	2N03L07

**Maximum Ratings, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Value	Unit
Continuous drain current <sup>1)</sup> $T_C=25^\circ\text{C}$	$I_D$	30 30	A
Pulsed drain current $T_C=25^\circ\text{C}$	$I_{D\text{ puls}}$	120	
Avalanche energy, single pulse $I_D=30\text{ A}$ , $V_{DD}=25\text{V}$ , $R_{GS}=25\Omega$	$E_{AS}$	250	mJ
Repetitive avalanche energy, limited by $T_{jmax}^{2)}$	$E_{AR}$	13	
Reverse diode $dv/dt$ $I_S=30\text{A}$ , $V_{DS}=24\text{V}$ , $di/dt=200\text{A}/\mu\text{s}$ , $T_{jmax}=175^\circ\text{C}$	$dv/dt$	6	kV/ $\mu\text{s}$
Gate source voltage	$V_{GS}$	$\pm 20$	V
Power dissipation $T_C=25^\circ\text{C}$	$P_{tot}$	136	W
Operating and storage temperature	$T_j, T_{stg}$	-55... +175	$^\circ\text{C}$
IEC climatic category; DIN IEC 68-1		55/175/56	

**Thermal Characteristics**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Characteristics</b>					
Thermal resistance, junction - case	$R_{thJC}$	-	0.7	1.1	K/W
Thermal resistance, junction - ambient, leaded	$R_{thJA}$	-	-	100	
SMD version, device on PCB:	$R_{thJA}$				
@ min. footprint		-	-	75	
@ 6 cm <sup>2</sup> cooling area <sup>3)</sup>		-	-	50	

**Electrical Characteristics, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Static Characteristics</b>					
Drain-source breakdown voltage $V_{GS}=0V, I_D=1mA$	$V_{(BR)DSS}$	30	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D=85\mu A$	$V_{GS(th)}$	1.2	1.6	2	
Zero gate voltage drain current $V_{DS}=30V, V_{GS}=0V, T_j=25^\circ C$ $V_{DS}=30V, V_{GS}=0V, T_j=125^\circ C$	$I_{DSS}$	-	0.01 10	1 100	$\mu A$
Gate-source leakage current $V_{GS}=20V, V_{DS}=0V$	$I_{GSS}$	-	1	100	
Drain-source on-state resistance $V_{GS}=4.5V, I_D=30A$	$R_{DS(on)}$	-	7.4	9.8	m $\Omega$
Drain-source on-state resistance $V_{GS}=10V, I_D=30A$	$R_{DS(on)}$	-	5.3	6.7	

<sup>1</sup>Current limited by bondwire ; with an  $R_{thJC} = 1.1K/W$  the chip is able to carry  $I_D= 111A$  at  $25^\circ C$ , for detailed information see app.-note ANPS071E available at [www.infineon.com/optimos](http://www.infineon.com/optimos)

<sup>2</sup>Defined by design. Not subject to production test.

<sup>3</sup>Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70  $\mu m$  thick) copper area for drain connection. PCB is vertical without blown air.



**Electrical Characteristics**

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic Characteristics**

Transconductance	$g_{fs}$	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ , $I_D = 30A$	29	58	-	S
Input capacitance	$C_{iss}$	$V_{GS} = 0V$ , $V_{DS} = 25V$ , $f = 1MHz$	-	1900	2530	pF
Output capacitance	$C_{oss}$		-	740	990	
Reverse transfer capacitance	$C_{rss}$		-	180	270	
Gate resistance	$R_G$		-	2.3	-	$\Omega$
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 15V$ , $V_{GS} = 10V$ , $I_D = 15A$ , $R_G = 3.6\Omega$	-	8	10	ns
Rise time	$t_r$		-	17	26	
Turn-off delay time	$t_{d(off)}$		-	62	77.5	
Fall time	$t_f$		-	47	59	

**Gate Charge Characteristics**

Gate to source charge	$Q_{gs}$	$V_{DD} = 24V$ , $I_D = 30A$	-	6	8	nC
Gate to drain charge	$Q_{gd}$		-	18	27	
Gate charge total	$Q_g$	$V_{DD} = 24V$ , $I_D = 30A$ , $V_{GS} = 0$ to $10V$	-	51	68	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 24V$ , $I_D = 30A$	-	3.1	-	V

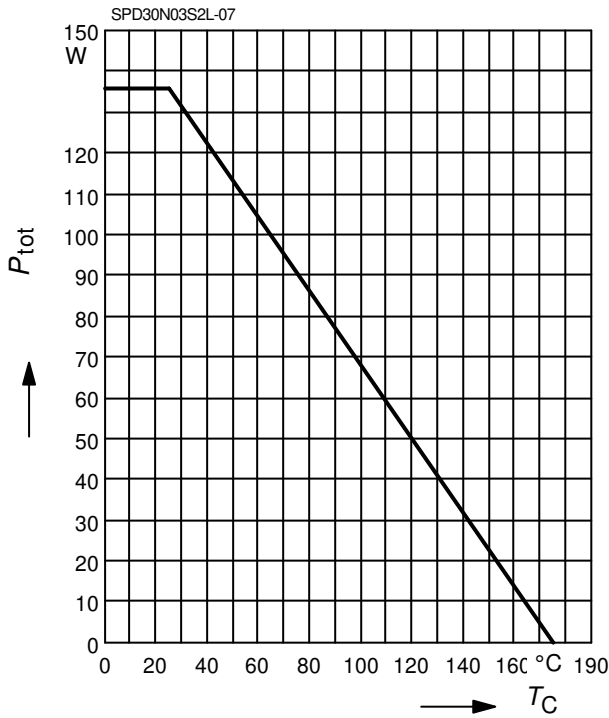
**Reverse Diode**

Inverse diode continuous forward current	$I_S$	$T_C = 25^\circ C$	-	-	30	A
Inv. diode direct current, pulsed	$I_{SM}$		-	-	120	
Inverse diode forward voltage	$V_{SD}$	$V_{GS} = 0V$ , $I_F = 30A$	-	0.9	1.3	V
Reverse recovery time	$t_{rr}$	$V_R = 15V$ , $I_F = I_S$ , $di_F/dt = 100A/\mu s$	-	41	51	ns
Reverse recovery charge	$Q_{rr}$		-	46	58	

**1 Power dissipation**

$P_{tot} = f(T_C)$

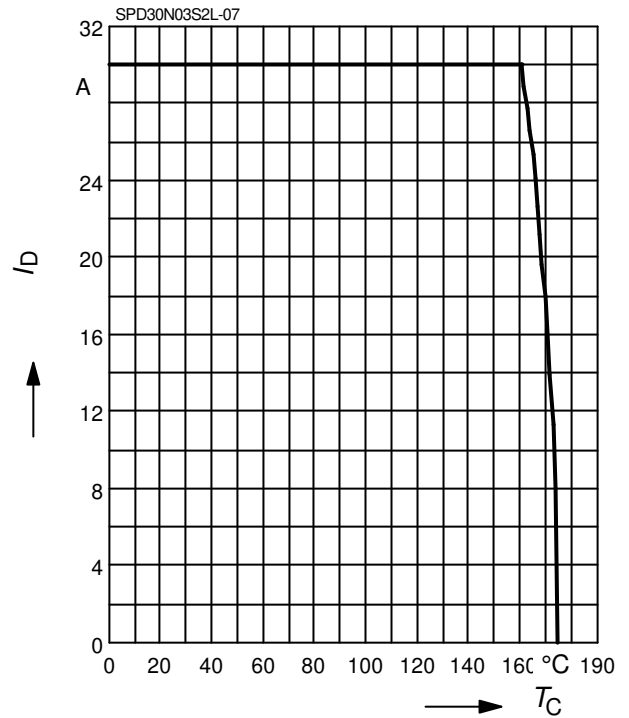
parameter:  $V_{GS} \geq 4 \text{ V}$



**2 Drain current**

$I_D = f(T_C)$

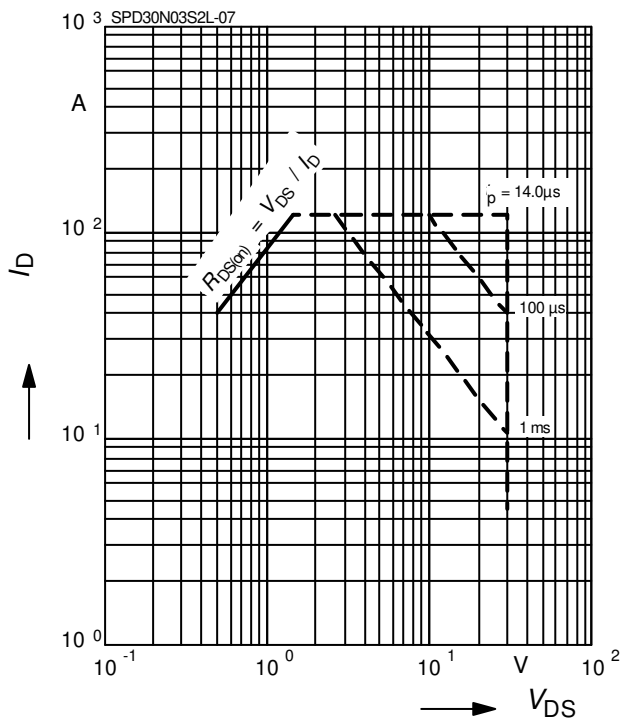
parameter:  $V_{GS} \geq 10 \text{ V}$



**3 Safe operating area**

$I_D = f(V_{DS})$

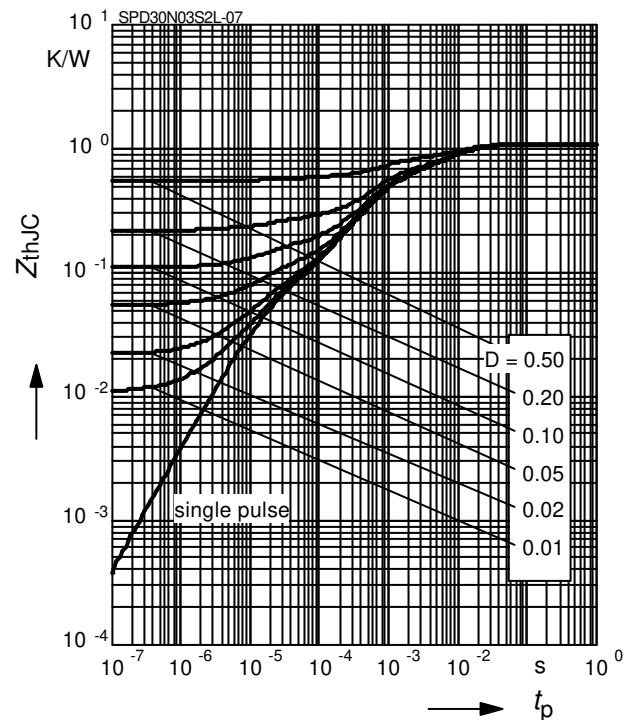
parameter:  $D = 0$ ,  $T_C = 25 \text{ °C}$



**4 Max. transient thermal impedance**

$Z_{thJC} = f(t_p)$

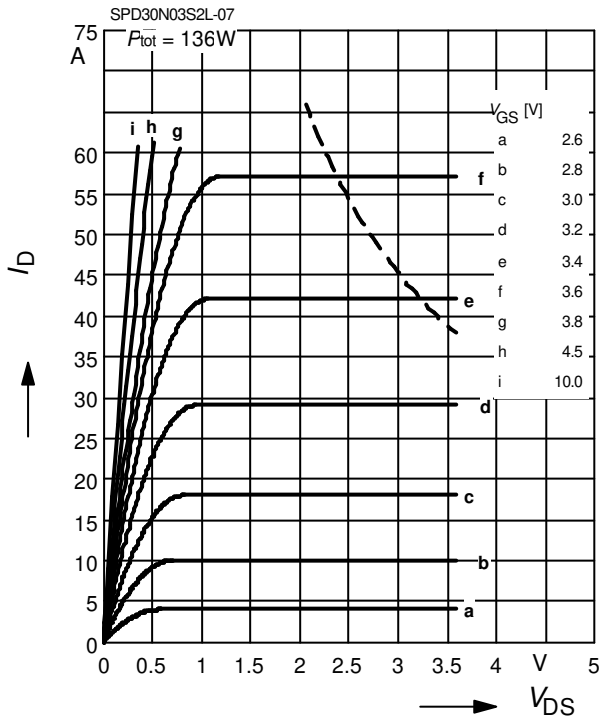
parameter:  $D = t_p/T$



**5 Typ. output characteristic**

$I_D = f(V_{DS}); T_J = 25^\circ\text{C}$

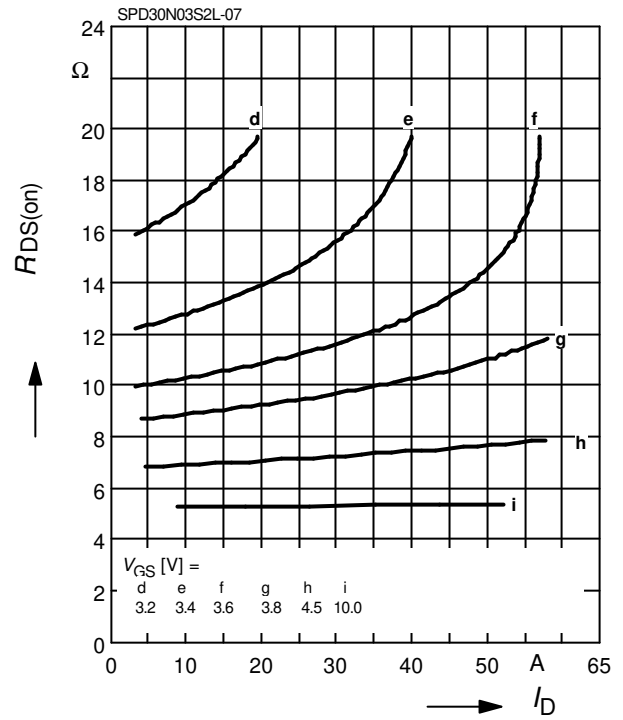
parameter:  $t_p = 80 \mu\text{s}$



**6 Typ. drain-source on resistance**

$R_{DS(\text{on})} = f(I_D)$

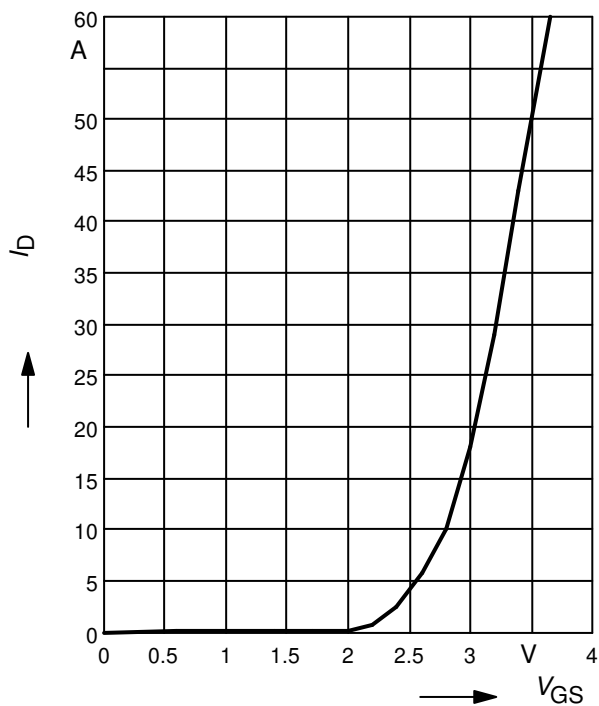
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(\text{on})\text{max}}$

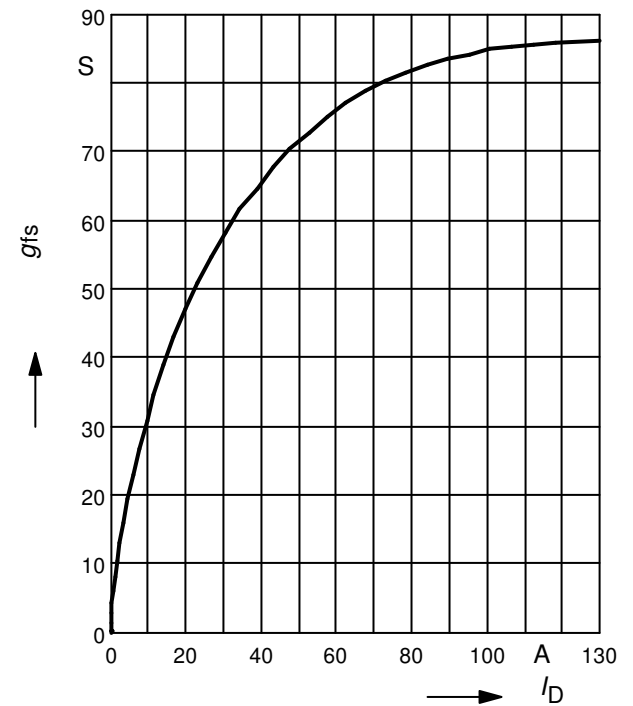
parameter:  $t_p = 80 \mu\text{s}$



**8 Typ. forward transconductance**

$g_{fs} = f(I_D); T_J = 25^\circ\text{C}$

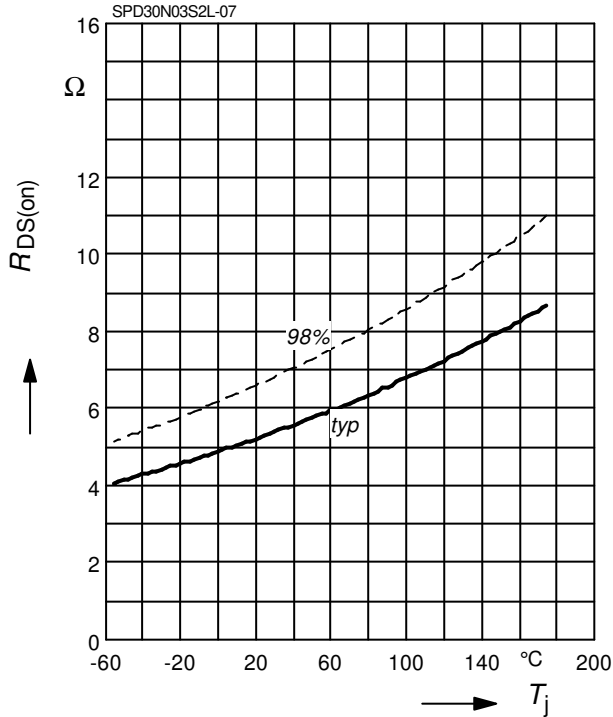
parameter:  $g_{fs}$



**9 Drain-source on-state resistance**

$$R_{DS(on)} = f(T_j)$$

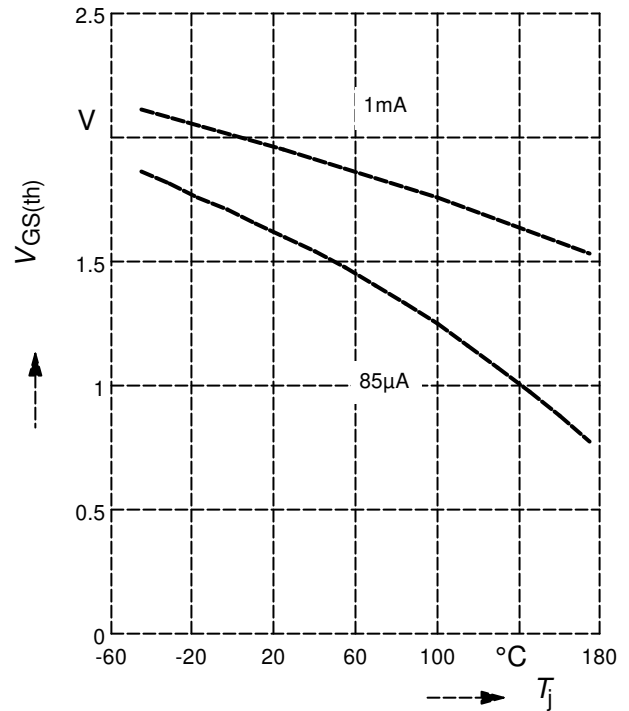
parameter :  $I_D = 30\text{ A}$ ,  $V_{GS} = 10\text{ V}$



**10 Typ. gate threshold voltage**

$$V_{GS(th)} = f(T_j)$$

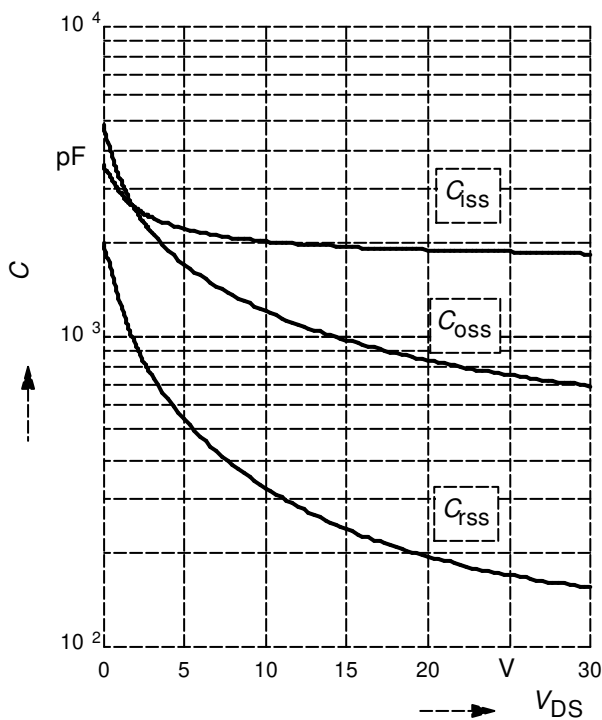
parameter:  $V_{GS} = V_{DS}$



**11 Typ. capacitances**

$$C = f(V_{DS})$$

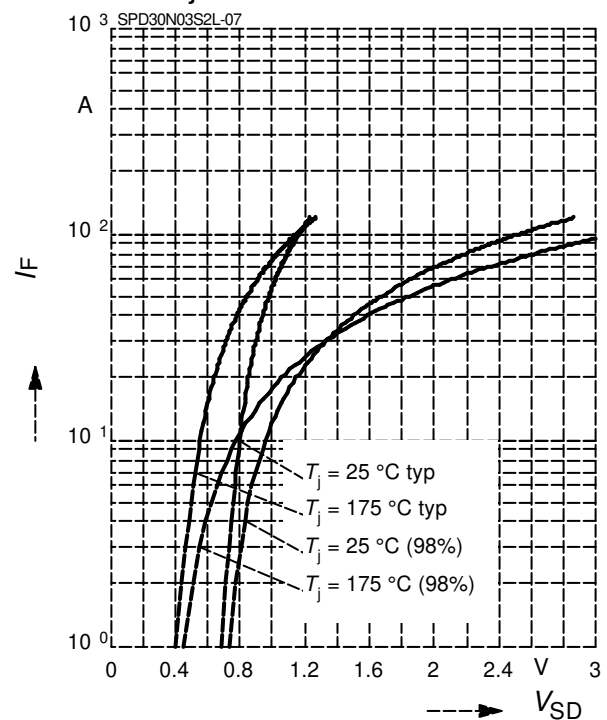
parameter:  $V_{GS}=0\text{V}$ ,  $f=1\text{ MHz}$



**12 Forward character. of reverse diode**

$$I_F = f(V_{SD})$$

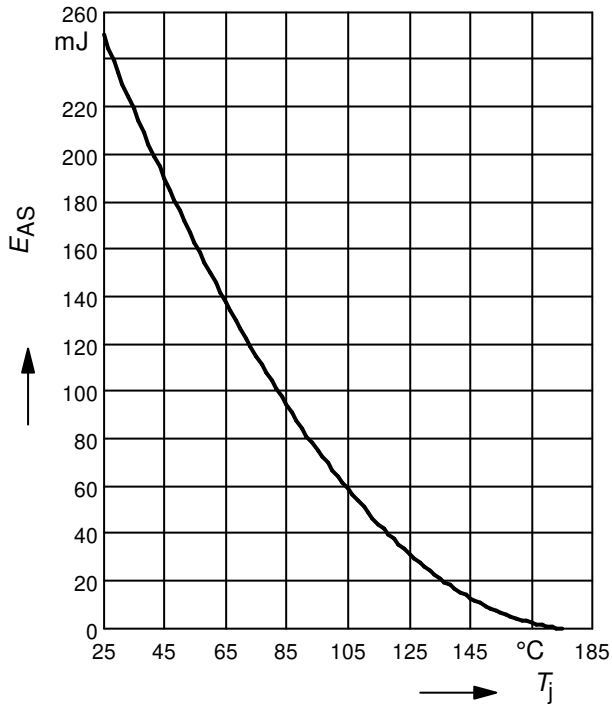
parameter:  $T_j$ ,  $t_p = 80\text{ }\mu\text{s}$



**13 Typ. avalanche energy**

$$E_{AS} = f(T_j)$$

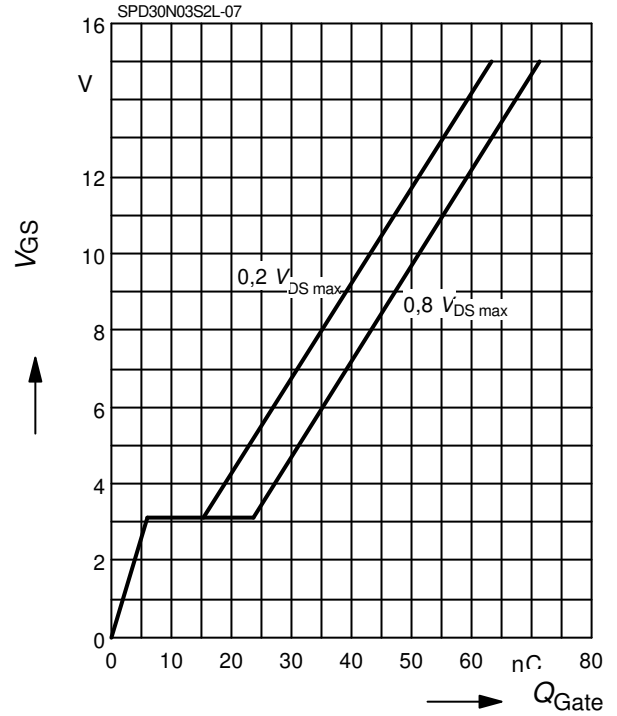
par.:  $I_D = 30\text{ A}$  ,  $V_{DD} = 25\text{ V}$  ,  $R_{GS} = 25\ \Omega$



**14 Typ. gate charge**

$$V_{GS} = f(Q_{Gate})$$

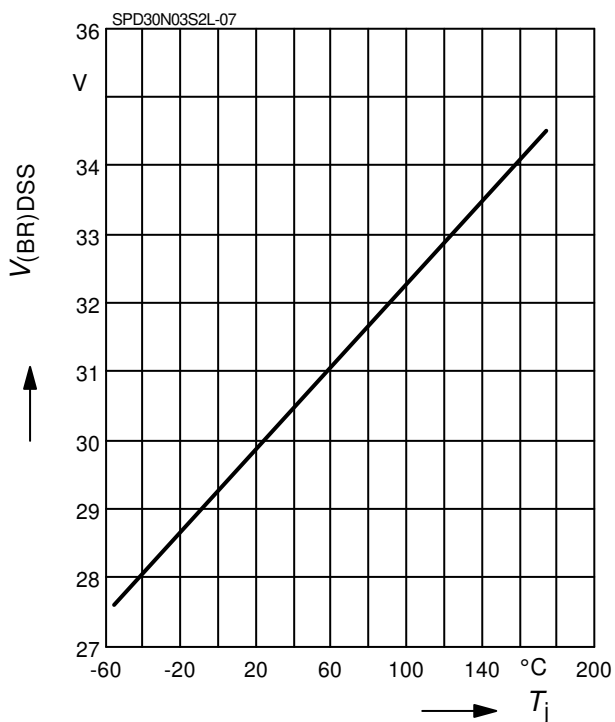
parameter:  $I_D = 30\text{ A}$  pulsed



**15 Drain-source breakdown voltage**

$$V_{(BR)DSS} = f(T_j)$$

parameter:  $I_D = 10\text{ mA}$





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